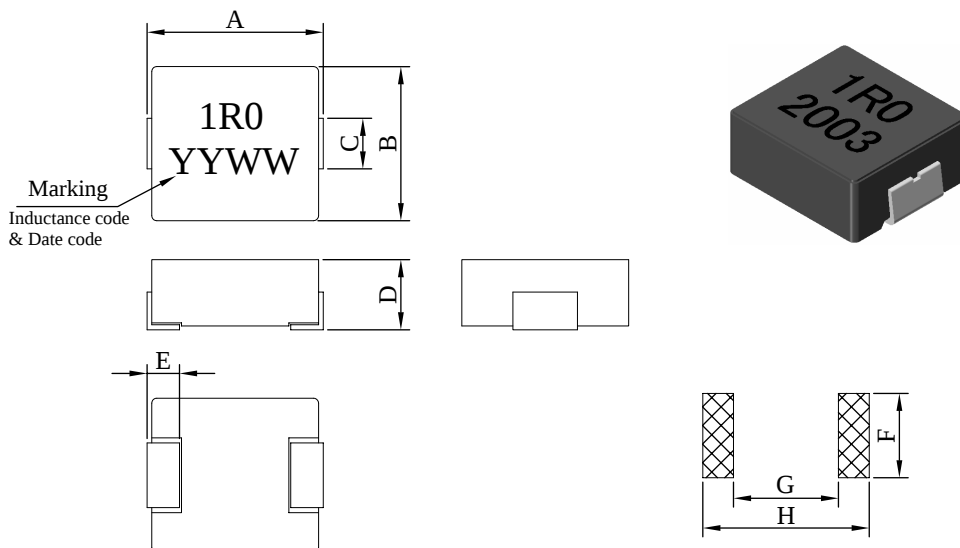


SPECIFICATION FOR APPROVAL

REF :

PROD. NAME	Shielded Smd Power Inductor	ABC'S DWG NO.		EH10630□□□□S□-□□□		
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I . Configuration and dimensions :



(PCB Pattern)

Unit : mm

A	B	C	D	E	F	G	H
7.30 ±0.30	6.60 ±0.30	3.00 ±0.3	2.80 ±0.2	1.80 ±0.3	3.50 ref.	2.50 ref.	8.40 ref.

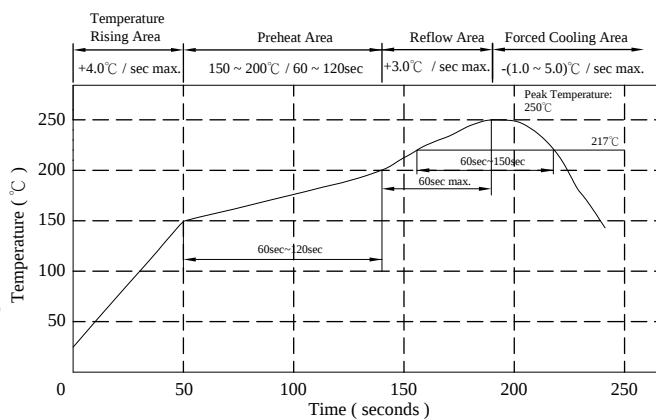
II . Description :

- a . Powder molding construction
- b . Magnetically shielded
- c . Wire : Polyester wire or equivalent
- d . Product weight : 0.70g (ref.)
- e . Products comply with RoHS' requirements
- f . Halogen free

Peak Temp : 250°C max.
Max. Peak Temp - 5°C : 30sec max.
Max time above 217°C : 60sec~150sec max.

III . General specification :

- a . Storage temp. : -40°C ----+125°C
- b . Operating temp. : -40°C ----+125°C
(Temp. rise included)
- c . Resistance to solder heat : 260°C .10 secs.



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SPECIFICATION FOR APPROVAL

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IV . Electrical characteristics :

DWG No.	Inductance (μ H)	Isat (A) typ.	Irms (A) typ.	RDC ($m\Omega$)	
				max.	typ.
EHI0630R10YSB-□□□	0.10 $\pm$ 30%	60.00	32.50	1.70	1.20
EHI0630R15YSB-□□□	0.15 $\pm$ 30%	45.00	27.00	1.90	1.50
EHI0630R22YSB-□□□	0.22 $\pm$ 30%	40.00	23.00	2.80	2.10
EHI0630R33MSB-□□□	0.33 $\pm$ 20%	32.00	20.00	3.90	3.50
EHI0630R47MSB-□□□	0.47 $\pm$ 20%	26.00	17.50	4.20	4.00
EHI0630R68MSB-□□□	0.68 $\pm$ 20%	25.00	15.50	5.50	4.80
EHI06301R0MSB-□□□	1.00 $\pm$ 20%	22.00	11.00	10.00	8.30
EHI06301R5MSB-□□□	1.50 $\pm$ 20%	18.00	9.00	15.00	13.00
EHI06302R2MSB-□□□	2.20 $\pm$ 20%	14.00	8.00	20.00	18.00
EHI06303R3MSB-□□□	3.30 $\pm$ 20%	13.50	6.00	30.00	28.00
EHI06304R7MSB-□□□	4.70 $\pm$ 20%	10.00	5.50	40.00	37.00
EHI06306R8MSB-□□□	6.80 $\pm$ 20%	8.00	4.50	60.00	54.00
EHI0630100MSB-□□□	10.00 $\pm$ 20%	6.00	3.50	85.00	75.00
EHI0630150MSB-□□□	15.00 $\pm$ 20%	4.00	3.00	123.00	107.00
EHI0630220MSB-□□□	22.00 $\pm$ 20%	3.50	2.00	190.00	165.00
EHI0630330MSB-□□□	33.00 $\pm$ 20%	2.50	2.00	240.00	200.00
EHI0630470MSB-□□□	47.00 $\pm$ 20%	2.00	1.75	363.00	302.00

- 1). Electrical specifications at 25°C
- 2). Measured frequency of inductance is 100 kHz / 1V
- 3). Isat base on $\Delta L/L0A=30\%$ typ. (Approximately transient current)
- 4). Irms base on Temp. rise 40°C typ.

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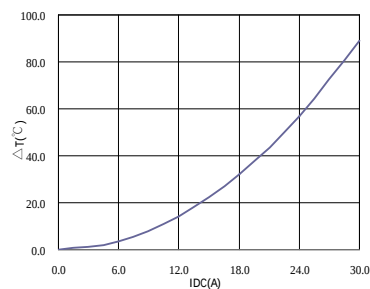
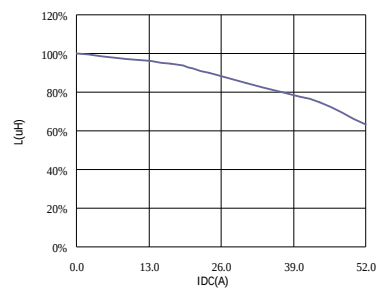
SPECIFICATION FOR APPROVAL

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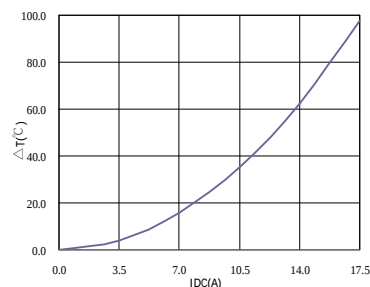
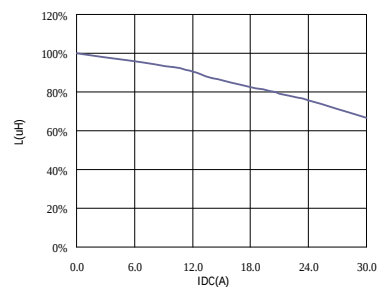
PROD. NAME	Shielded Smd Power Inductor	ABC'S DWG NO.		EHI0630□□□□S□-□□□		
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V . Curve :

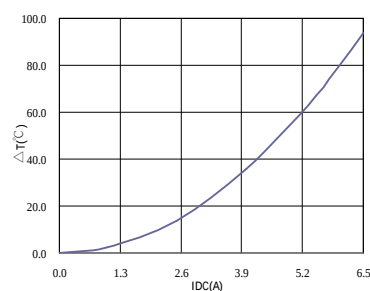
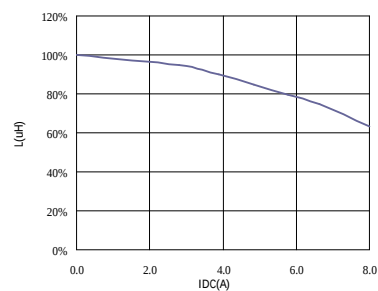
EHI0630R33MSB



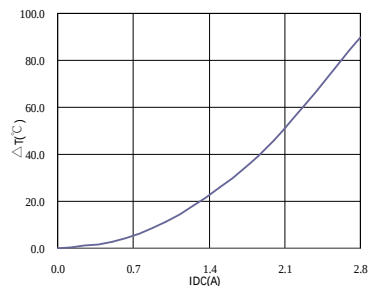
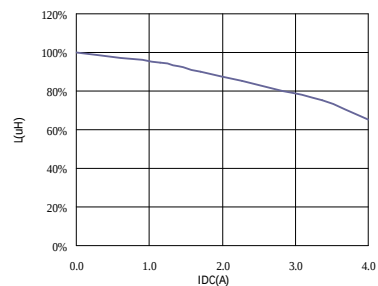
EHI06301R0MSB



EHI0630100MSB



EHI0630470MSB



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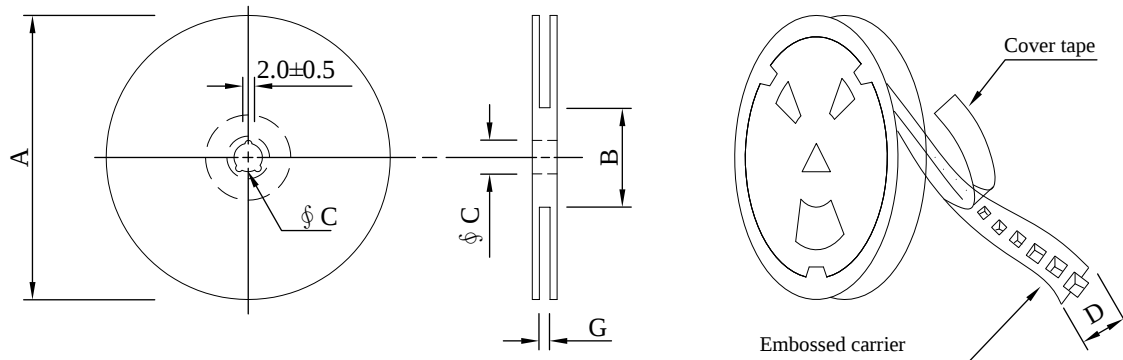
SPECIFICATION FOR APPROVAL

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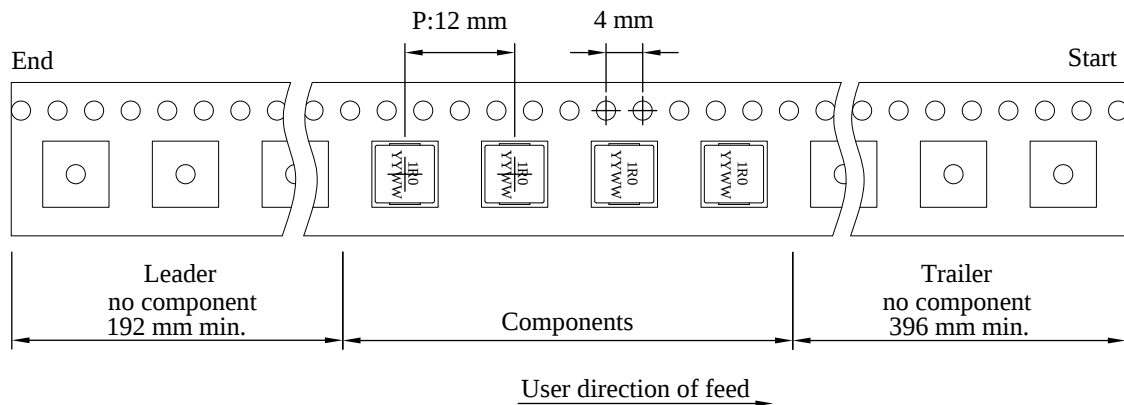
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		REV.	20210412-C	PAGE	4	

VI . Packaging information :

(1) Configuration



※Carrier tape width : D



(2) Dimensions

Unit:mm

Style	A	B	C	D	G
13 - 16	330	100 ±0.2	13 ^{+0.5} _{-0.2}	16	16.4 ⁺² ₋₀

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (g)	Style	Q'TY (pcs)	G.W. (kg)	Size (cm)
B	1,000	1,100	13 - 16	12,000	18.0	38 x 37 x 22

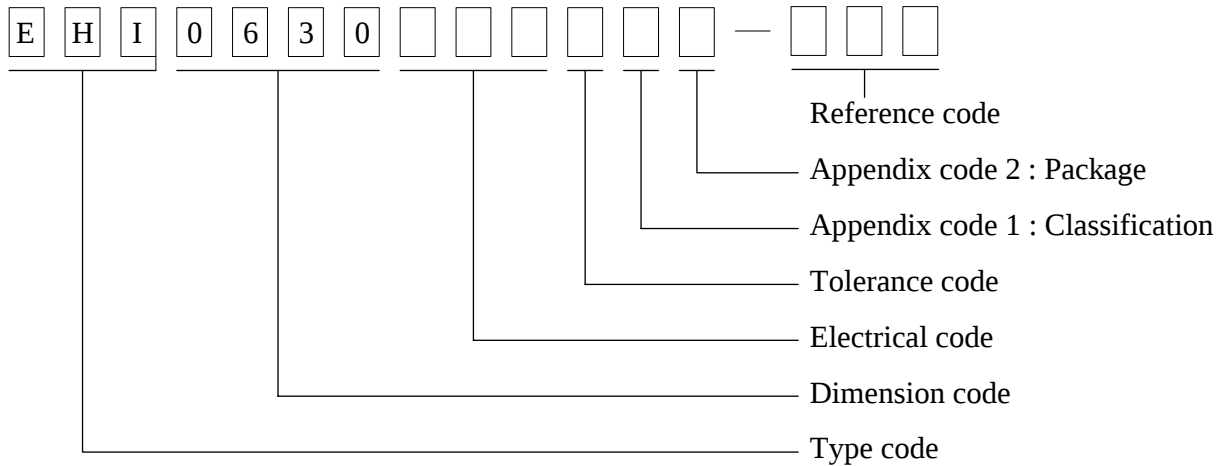
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SPECIFICATION FOR APPROVAL

REF :

PROD. NAME	Shielded Smd Power Inductor	ABC'S DWG NO.		EHI0630□□□□S□-□□□		
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VII . Drawing number expression :



Appendix code 1 : Product Classification

Appendix code 2 : Package Information

Code	Inner package	Cover tape	Carrier tape	Bag	Package Q'TY	Remark
B	T / R (Reel package)	Heat seal	Antistatic	Antistatic	1,000 pcs	

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SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Shielded Smd Power Inductor	ABC'S DWG NO.		EHI0630□□□□S□-□□□		
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VIII . Reliability test :

Item	Reference documents	Test Condition	Test Specification
1.High Temperature Exposure	MIL-STD-202 Method 108	1.Temperature: 125±2℃ 2.Time:96±2 hours.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
2.Temperature Cycling	JESD22-A 104	1.Temperature: -40℃ ~ +125℃ 2.Number of cycle:100 cycle 3.Dwell time:30 minutes	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
3.Biased Humidity Test	MIL-STD-202 Method 103	1.Temperature : 85±2 ℃ 2.Humidity: 85% RH. 3.Time:96±2 Hours	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
4.Operational Life	JESD22-A 108	1.Temperature: 125℃(Temp. rise included) 2.Time:96±2 hours. 3.Rated current	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
5.External Visual	JESD22-B 101 & MIL-STD-883 Method 2009	Inspect product constructions, marking and workmanship.	1.No pollution on the surface of products. 2.Clear marking. 3.No crack.
6.Physical Dimensions	JESD22-B 100	Verify physical dimensions to the applicable product detail specification.	Per product specification standard
7.Resistance to solvents	MIL-STD-202 Method 215	Immerse into solvent for 3±0.5 minutes & brush 10 times for 3 cycles.	1.No body change in apperance. 2.No marking blurred. 3.Inductance shall not change more than ±20%.
8.Vibration Test	MIL-STD-202 Method 204	1.Frequency and Amplitued : 10-2000-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
9.Resistance To Soldering Heat Test	MIL-STD-202 Method 210 & J-STD020D.1	1.Highest temperature : 250±5℃. 2.Time (temp. ≥ 217℃) : 60~150 Second. 3.IR reflow times : 3 times.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
10.Saturation Current	JIS C 6436 & User SPEC.	1.Applied rated current for 5 second. 2.Saturation current	Inductance shall not drop more than 30% typ.
11.Over load	JIS C 6436 & User SPEC.	1.Applied one and half rated current for a period of 5 minutes. 2.Rated current	No electrical or mechanical damage
12.Temperature Rise Current	JIS C 6436 & User SPEC.	1.Applied rated current for 10 minutes. 2.Temperature measure by digital surface thermometer. 3.Irms current	Surface temperature rise is less than 40℃ typ.
13.Solderability Test	J-STD-002 & JESD22-B 102	1.Baking in pre-testing : 150±5℃ / 16Hours±30 min. 2.Peak temperature : 240±5℃ 3.Time (temp. ≥ 217℃) : 60~150 second. 4.IR reflow times : 1 times.	More than 95% soldering coverage min on terminations.
14.Electrical Characteriazation	MIL-STD-202 Method 304 & User SPEC.	1.Operating temperature : -40℃~125℃ 2.Room temperature : 25℃.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
15.Drop	CNS-C6354 & GB/T 2423.8	1.Products shall be mounted on SPEC. PCB and dropped down from a height of 1m 2.Drop total time : 6 time (Every side of sample drop 2 time)	1. Adhesion on PCB shall be enough. 2. Product appearance shall not break. 3. No electrical damage.
16.Terminal Strength Test	IEC 60068-2-21	1.Apply push force to samples mounted on PCB. 2.Force of 1.8 kg for 60±1 seconds.	After test, inductors shall be no mechanical damage.

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